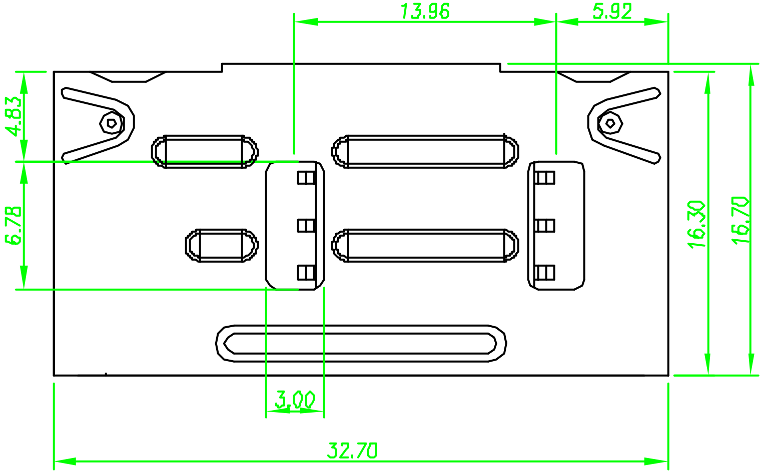
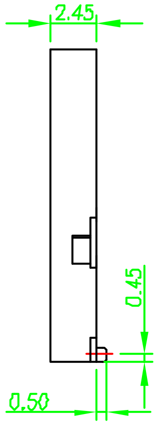
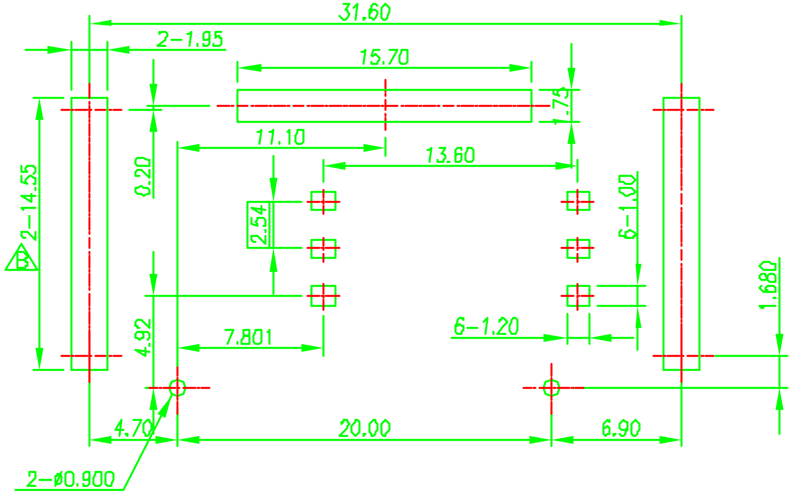
更改 REV	設 變 內 容 MODIFICATION	日 期 DATE	修 改 DRAW
B	SMT面延長	91.11.27	MK LEE

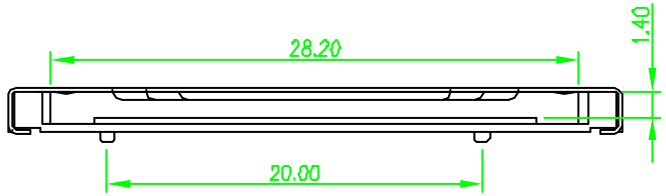


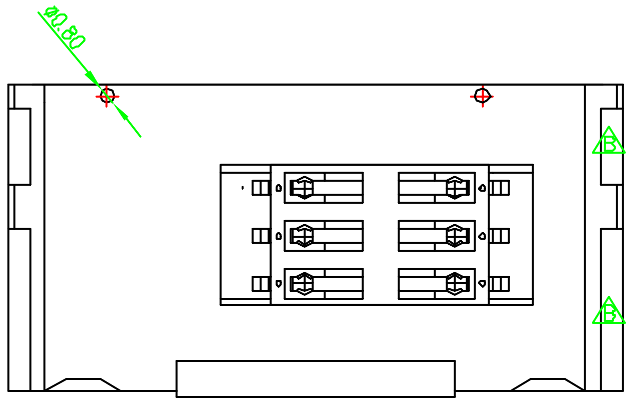




P.C.B. LAYOUT (TOP VIEW)

(.XX±0.05)(.XXX±0.030)





NOTES:

1. Materials:
   Housing: LCP
   Contact: Phosphor Bronze
   Shell: Phosphor Bronze
2. Plating:
   Contact Area Selective Gold 30u".
   Solder tails area: 100u" Tin/Lead
   Underplate: 50u" Nickel

DIMENSION IN mm [Inch]		
TOLERANCE UNLESS OTHERWISE SPECIFIED		
.X±0.3	X.°± 1°	審 核 APPROVE
.XX±0.20	.X°± 0.5°	核 對 CHECK
.XXX±0.100	.XX°± 0.25°	製 圖 DRAW

C	康茂股份有限公司 COMMA ELECTRONIC INC.		
名稱 TITLE	SIM CARD CONNECTOR	CUSTOMER DRAWING	
案 號 FILE NO. SCS2.54−2106	圖 號 DWG NO. SCS2.54−2106		
圖紙 SIZE A4	角法 PROJ.	張數 SHEET 1 / 1	
	比例 SCALE 1:1	更改 REV B	

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